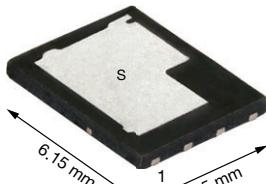
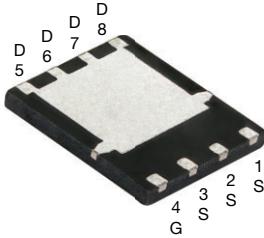


N-Channel 100 V (D-S) 175 °C MOSFET

PowerPAK® SO-8DC


Top View



Bottom View

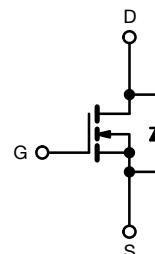
FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low $R_{DS(on)} \times Q_g$ figure-of-merit (FOM)
- Tuned for the lowest $R_{DS(on)} \times Q_{oss}$ FOM
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converters
- Power supplies
- Motor drive control
- Battery and load switch



N-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	100
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.0061
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5$ V	0.0072
Q_g typ. (nC)	35.1
I_D (A)	90.5
Configuration	Single

ORDERING INFORMATION

Package	PowerPAK SO-8DC
Lead (Pb)-free and halogen-free	SiDR104AEP-T1-RE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	100	V
Gate-source voltage	V_{GS}	± 20	
Continuous drain current ($T_J = 150$ °C)	I_D	90.5	
		75.7	
		21.1 b, c	
		17.7 b, c	
Pulsed drain current ($t = 100$ μ s)	I_{DM}	200	A
Continuous source-drain diode current	I_S	109	
		5.9 b, c	
Single pulse avalanche current	I_{AS}	35	
Single pulse avalanche energy	E_{AS}	61	mJ
Maximum power dissipation	P_D	120	
		84	
		6.5 b, c	
		4.5 b, c	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) c		260	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b	R_{thJA}	18	23	
Maximum junction-to-case (drain)	R_{thJC}	1	1.25	°C/W
Maximum junction-to-case (source)	R_{thJC}	1.4	1.75	

Notes

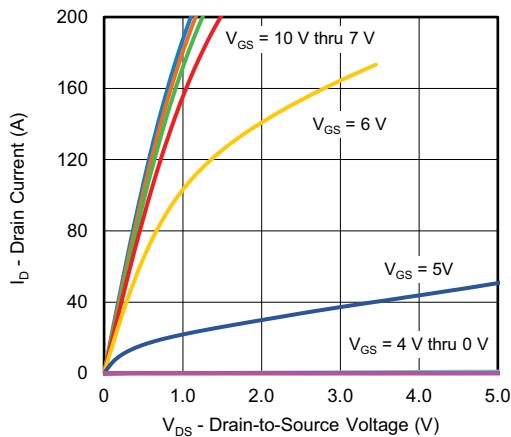
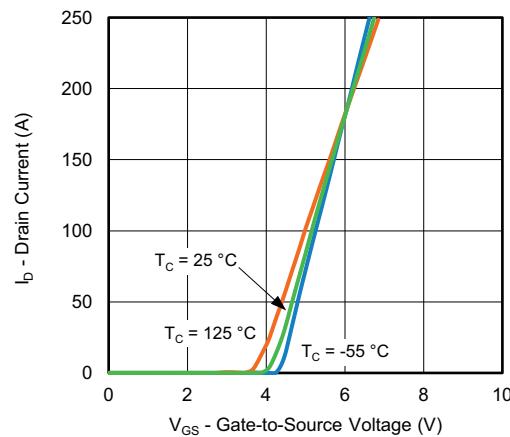
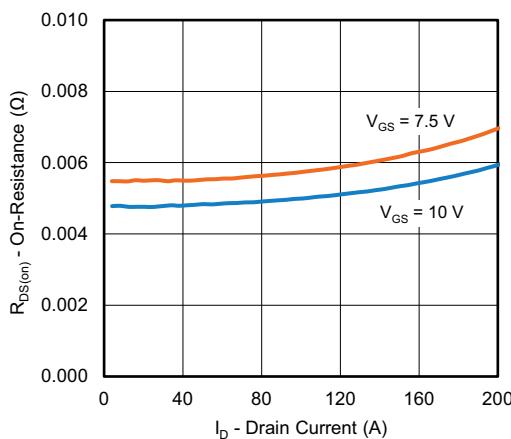
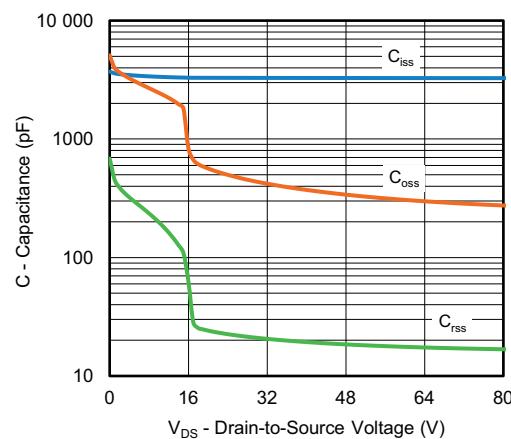
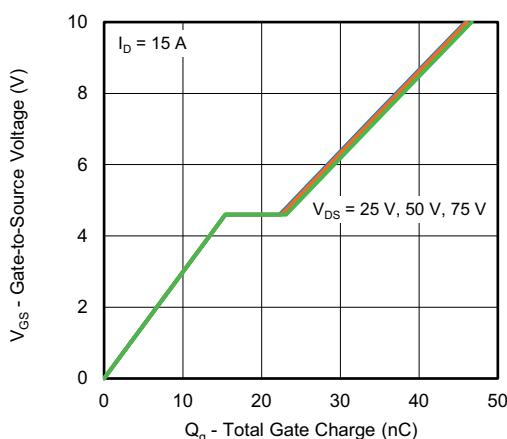
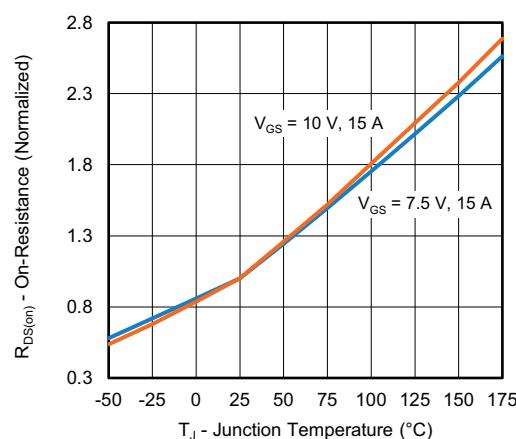
- Package limited
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?273257). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W
- $T_C = 25$ °C

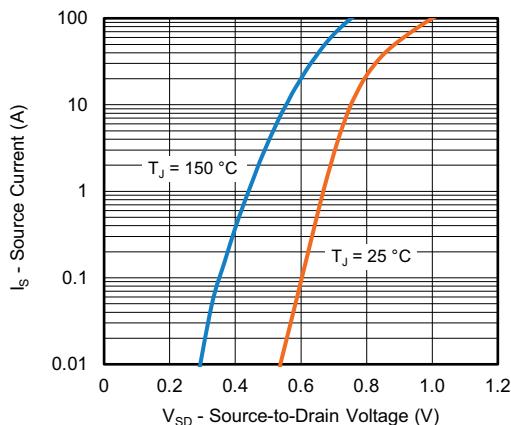
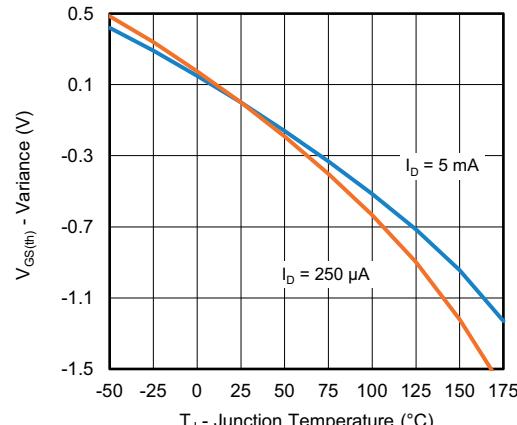
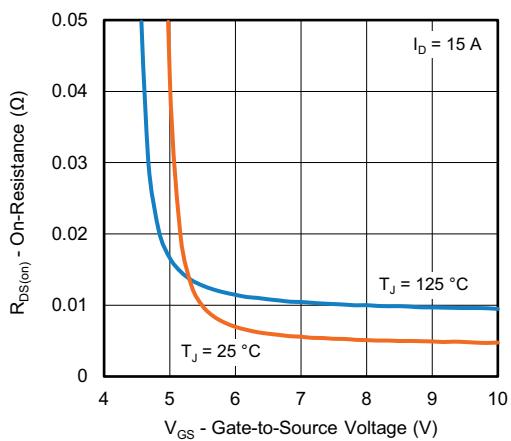
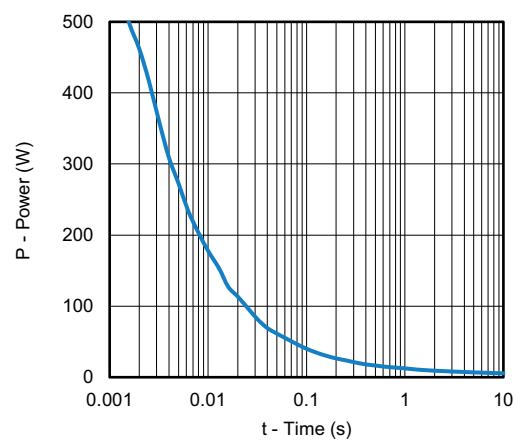
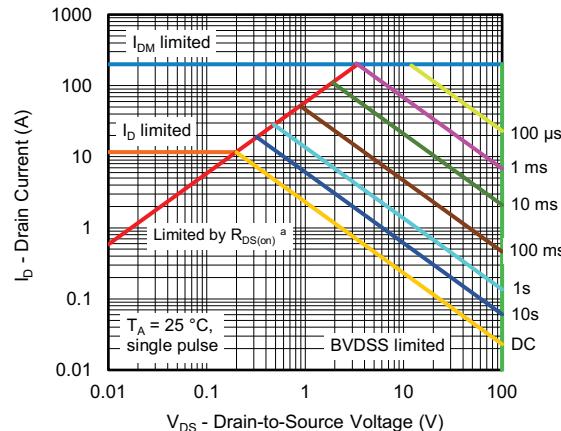
SPECIFICATIONS ($T_J = 25^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 1 \text{ mA}$	100	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 1 \text{ mA}$	-	62	-	$\text{mV}/^\circ\text{C}$
$V_{GS(\text{th})}$ temperature coefficient	$\Delta V_{GS(\text{th})}/T_J$	$I_D = 250 \mu\text{A}$	-	-8	-	
Gate-source threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2	-	4	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 20 \text{ V}$	-	-	100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 100 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 70^\circ\text{C}$	-	-	15	
On-state drain current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 10 \text{ V}$, $V_{GS} = 10 \text{ V}$	40	-	-	A
Drain-source on-state resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$, $I_D = 15 \text{ A}$	-	0.0049	0.0061	Ω
		$V_{GS} = 7.5 \text{ V}$, $I_D = 15 \text{ A}$	-	0.0055	0.0072	
Forward transconductance ^a	g_{fs}	$V_{DS} = 15 \text{ V}$, $I_D = 15 \text{ A}$	-	75	-	S
Dynamic ^b						
Input capacitance	C_{iss}	$V_{DS} = 50 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	-	3250	-	pF
Output capacitance	C_{oss}		-	335	-	
Reverse transfer capacitance	C_{rss}		-	18.5	-	
Total gate charge	Q_g	$V_{DS} = 50 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 15 \text{ A}$	-	46.1	70	nC
Gate-source charge	Q_{gs}	$V_{DS} = 50 \text{ V}$, $V_{GS} = 7.5 \text{ V}$, $I_D = 15 \text{ A}$	-	35.1	53	
Gate-drain charge	Q_{gd}		-	15.4	-	
Output charge	Q_{oss}		-	7.1	-	
Gate resistance	R_g	$V_{DS} = 50 \text{ V}$, $V_{GS} = 0 \text{ V}$	-	59.5	-	Ω
Turn-on delay time	$t_{d(\text{on})}$	$V_{DD} = 50 \text{ V}$, $R_L = 3.33 \Omega$, $I_D \geq 15 \text{ A}$, $V_{GEN} = 10 \text{ V}$, $R_g = 1 \Omega$	-	0.3	0.9	
Rise time	t_r		-	17	34	
Turn-off delay time	$t_{d(\text{off})}$		-	7	14	
Fall time	t_f		-	28	56	
Turn-on delay time	$t_{d(\text{on})}$	$V_{DD} = 50 \text{ V}$, $R_L = 3.33 \Omega$, $I_D \geq 15 \text{ A}$, $V_{GEN} = 7.5 \text{ V}$, $R_g = 1 \Omega$	-	8	16	ns
Rise time	t_r		-	21	42	
Turn-off delay time	$t_{d(\text{off})}$		-	8	16	
Fall time	t_f		-	25	50	
-	-	-	-	10	20	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25^\circ\text{C}$	-	-	90	A
Pulse diode forward current	I_{SM}		-	-	200	
Body diode voltage	V_{SD}	$I_S = 5 \text{ A}$, $V_{GS} = 0 \text{ V}$	-	0.74	1.1	V
Body diode reverse recovery time	t_{rr}	$I_F = 15 \text{ A}$, $\text{di}/\text{dt} = 100 \text{ A}/\mu\text{s}$, $T_J = 25^\circ\text{C}$	-	45	90	ns
Body diode reverse recovery charge	Q_{rr}		-	65	130	nC
Reverse recovery fall time	t_a		-	30	-	
Reverse recovery rise time	t_b		-	15	-	ns

Notes

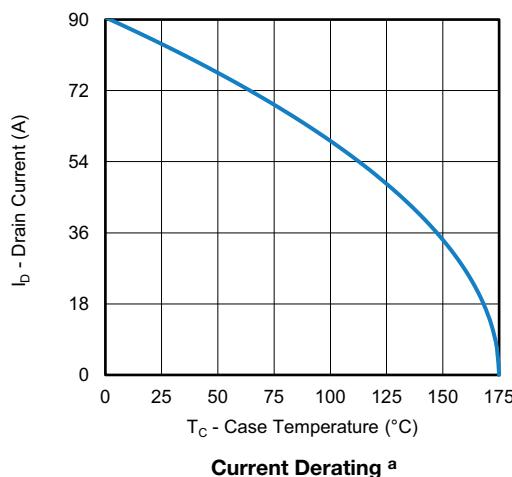
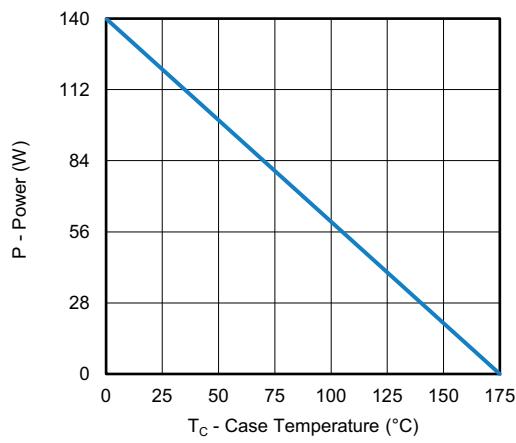
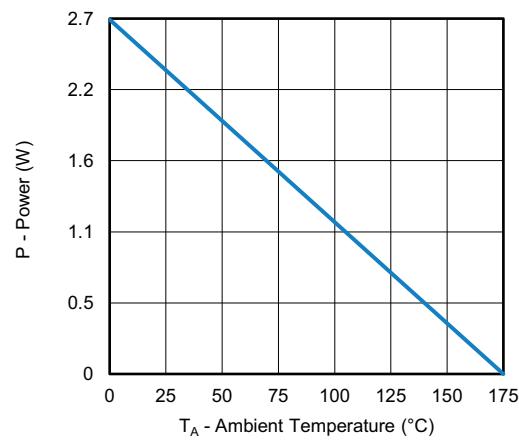
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

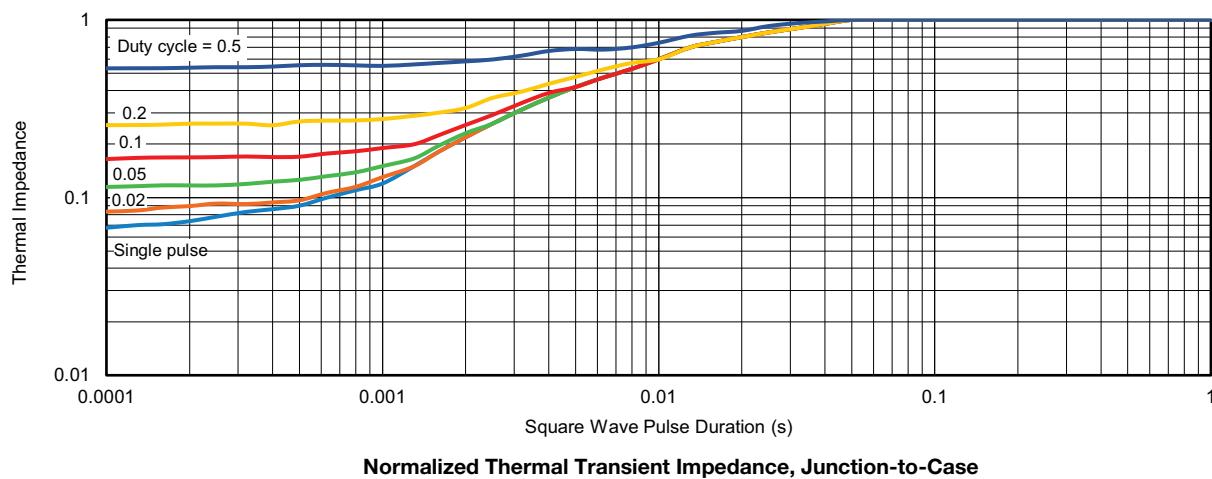
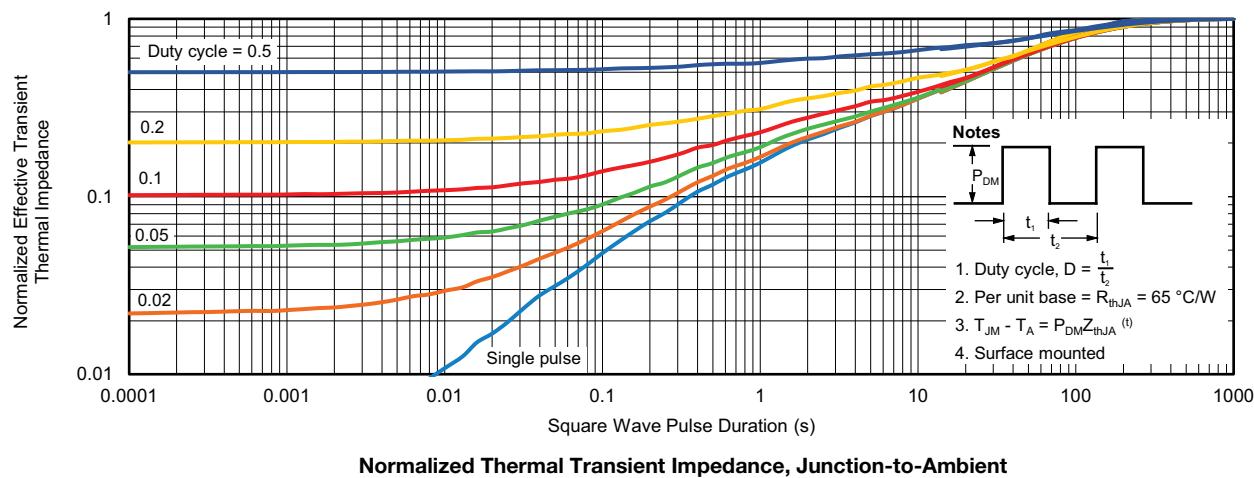
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Source-Drain Diode Forward Voltage

Threshold Voltage

On-Resistance vs. Gate-to-Source Voltage

Single Pulse Power, Junction-to-Ambient

Safe Operating Area, Junction-to-Ambient
Note

a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

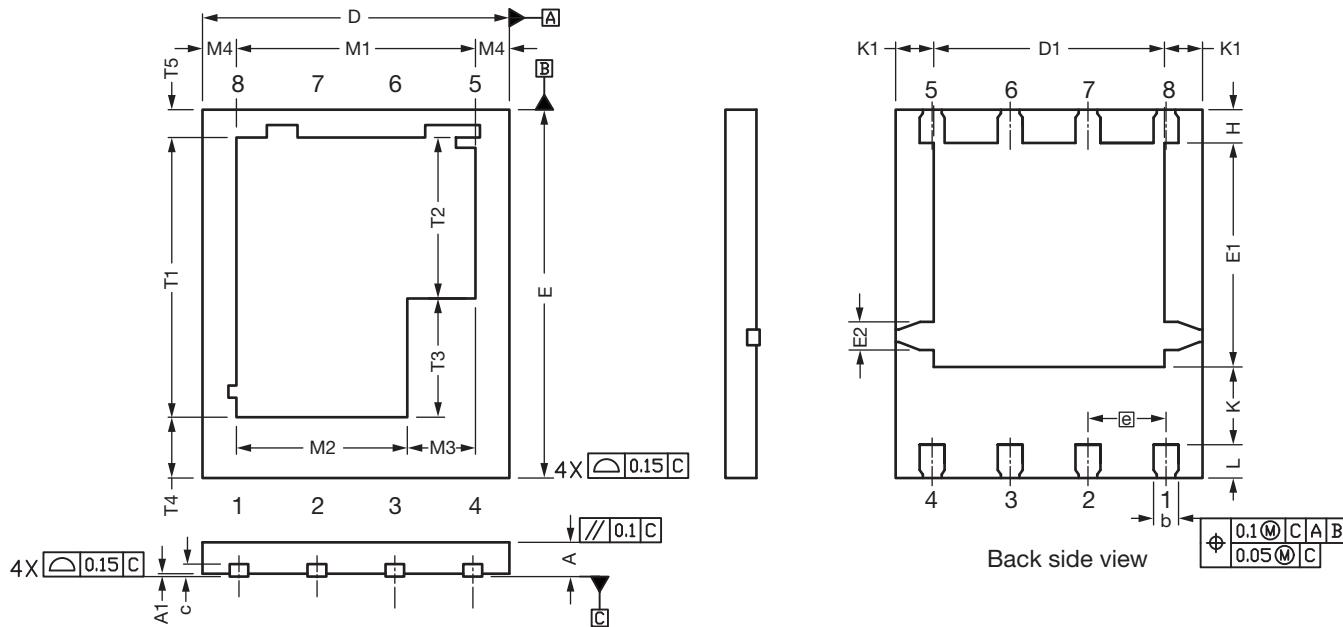
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating ^a

Power, Junction-to-Case

Power, Junction-to-Ambient
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63069.

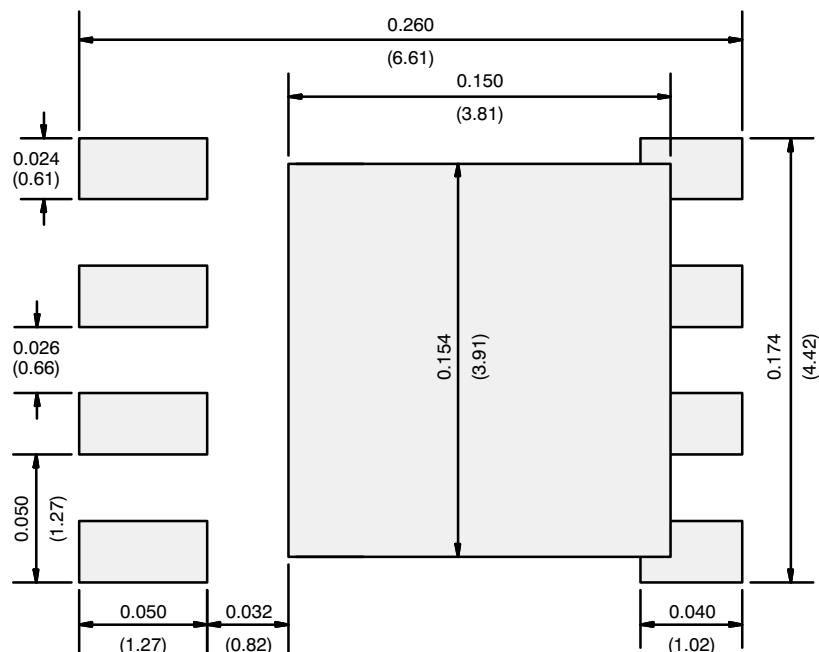
PowerPAK® SO-8 Double Cooling Case Outline



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.51	0.56	0.61	0.020	0.022	0.024
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.36	0.41	0.46	0.014	0.016	0.018
c	0.15	0.20	0.25	0.006	0.008	0.010
D	4.90	5.00	5.10	0.193	0.197	0.201
D1	3.71	3.76	3.81	0.146	0.148	0.150
e	1.27 BSC			0.050 BSC		
E	5.90	6.00	6.10	0.232	0.236	0.240
E1	3.60	3.65	3.70	0.142	0.144	0.146
E2	0.46 typ.			0.018 typ.		
H	0.49	0.54	0.59	0.019	0.021	0.023
K	1.22	1.27	1.32	0.048	0.050	0.052
K1	0.64 typ.			0.025 typ.		
L	0.49	0.54	0.59	0.019	0.021	0.023
M1	3.8	3.90	4.00	0.150	0.154	0.158
M2	2.69	2.79	2.89	0.106	0.110	0.114
M3	1.01	1.11	1.21	0.040	0.044	0.048
M4	0.56 typ.			0.022 typ.		
N	8			8		
T1	4.46	4.56	4.66	0.176	0.180	0.184
T2	2.53	2.63	2.73	0.100	0.104	0.108
T3	1.83	1.93	2.03	0.072	0.076	0.080
T4	0.97 typ.			0.038 typ.		
T5	0.48 typ.			0.019 typ.		

ECN: T24-0304-Rev. C, 29-Jul-2024

DWG: 6048

RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single

Recommended Minimum Pads
Dimensions in Inches/(mm)

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